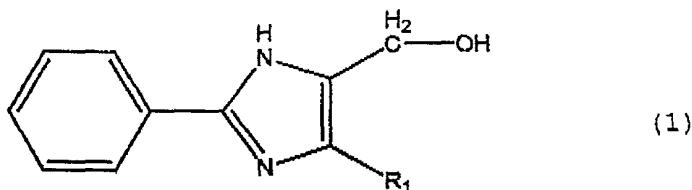


What is claimed is:

1. A paste for filling a throughhole, which comprises:
an epoxy resin; a curing agent; and a metal filler, wherein
the metal filler is a powder comprising a base metal, and the
curing agent is an imidazole compound represented by the
following formula (1):



wherein R₁ represents a hydrogen atom, an alkyl group having
10 1 to 10 carbon atoms, a hydroxyalkyl group having 1 to 10 carbon
atoms or an alkyloxy group having 1 to 10 carbon atoms.

2. The paste for filling a throughhole according to claim 1, which further comprises an inorganic filler.

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3. The paste for filling a throughhole according to claim 1 or 2, which further comprises an ultrafine inorganic filler.

4. The paste for filling a throughhole according to claim 20 3, wherein the ultrafine inorganic filler has a specific surface area by BET method of 40 to 400 m²/g.

5. The paste for filling a throughhole according to claim
3, wherein the ultrafine inorganic filler has a specific surface
area by BET method of 60 to 100 m²/g.

5 6. The paste for filling a throughhole according to claim
3, wherein the ultrafine inorganic filler has a primary particle
size of 5 to 50 nm.

10 7. The paste for filling a throughhole according to claim
3, wherein the ultrafine inorganic filler has a primary particle
size of 10 to 20 nm.

15 8. The paste for filling a throughhole according to claim
3, wherein the ultrafine inorganic filler has an apparent
specific gravity of 30 to 200 g/l.

20 9. The paste for filling a throughhole according to claim
3, wherein a 4% dispersion of the ultrafine inorganic filler
in 1:1 solution of water and methanol shows a pH value of 4.5
to 6.5.

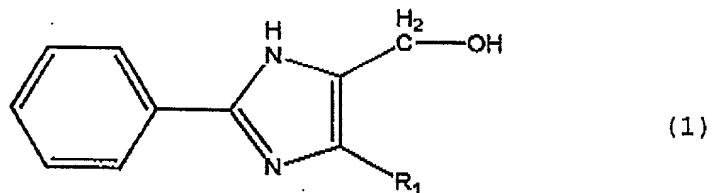
10. The paste for filling a throughhole according to claim
3, wherein the ultrafine inorganic filler contains an organic
ingredient in an amount of 3 to 5% by weight in terms of carbon.

11. The paste for filling a throughhole according to claim
3, wherein the ultrafine inorganic filler has a water content
of 0.05 to 0.15% by mass.

5 12. The paste for filling a throughhole according to claim
3, wherein the ultrafine inorganic filler comprises at least
one inorganic ingredient including a major inorganic ingredient,
and the ratio of the major inorganic ingredient is 99.5 mass%
or more based on the total of the at least one inorganic
10 ingredient.

13. A printed wiring board comprising: a substrate having
a conductor layer; and a throughhole penetrating through the
substrate,

15 wherein the throughhole is filled with a paste to be
subjected to curing; the paste comprises an epoxy resin, a
curing agent and a metal filler; the metal filler is a powder
comprises a base metal; and the curing agent is an imidazolic
compound represented by the following formula (1):



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wherein R₁ represents a hydrogen atom, an alkyl group containing

1 to 10 carbon atoms, a hydroxyalkyl group containing 1 to 10 carbon atoms or an alkyloxy group containing 1 to 10 carbon atoms.

5 14. The printed wiring board according to claim 13,
wherein the paste further comprises an inorganic filler.

10 15. The printed wiring board according to claim 13,
wherein the paste further comprises an ultrafine inorganic
filler.

15 16. The printed wiring board according to claim 13,
wherein at least part of the surface of the conductor layer
has been subjected to a treatment of imparting hydrophobicity
so that the treated surface part has a contact angle against
water of 90 degrees or higher.

20 17. The printed wiring board according to claim 13, wherein
at least part of the conductor layer has been subjected to a
roughing treatment so that the treated surface part has a
roughness: Rz of 0.3 to 20 μm .

25 18. The printed wiring board according to claim 13, wherein
the substrate comprises a core substrate having on at least
one side thereof a build-up layer formed by alternately

laminating an insulating layer and a conductor layer, and the throughhole penetrates through both the core substrate and the build-up layer.

5 19. A multi-layer printed wiring board, which comprises a printed wiring board according to claim 13, and a build-up layer formed by alternately laminating an insulating layer and a conductor layer.

10 20. The multi-layer printed wiring board according to claim 19, wherein the multi-layer wiring board is a PGA type wiring board.